

Griffin™ 5-R Series MWIR Camera Core

VGA5-R and HD5-R MWIR Camera Cores with Low System SWaP-C





The Griffin[™] 5-R Series camera cores include the Griffin[™] VGA5-R (640x512) and Griffin[™] HD5-R (1280x1024), featuring the industry's smallest MWIR sensors made to enable the smallest of cryocooled infrared imaging systems. The Griffin[™] 5-R Series captures snapshot MWIR imagery using Attollo Engineering's HOT Type-II Superlattice (T2SL) detector material. The extremely small pixel pitch of 5 µm enables more pixels on target with a short focal length optic, reducing overall sensor size. The Griffin[™] 5-R series uses a rotary cooler for fast cooldown and high power efficiency. The Griffin[™] VGA5-R and Griffin[™] HD5-R sensors are also capable of supporting broadband imaging along with day and night laser see-spot capabilities. The Griffin[™] 5-R series MWIR Cores are built for low SWaP applications and offers a significant opportunity for cost savings at the system level compared to competing MWIR cameras. With a volume of 134 cm³ and weight of 221 grams, these rotary cooled cameras are ideal for small gimbal integration as well as use in SWaP-constrained handheld and soldier-carried systems.

Highlights

- Technology: HOT T2SL MWIR provides imagery with smaller cooler $3-5.2 \ \mu m$ (MW) and $0.9-5.2 \ \mu m$ (SW/MW) wavelength bands
- Small pitch: 640 x 512, 5 μm and 1280 x 1024, 5 μm pixel pitch reduces the lens size
- Small: 4.2 x 4.6 x 8.6 cm and 221 grams
- Fast cooldown: 2.5 minutes to operating temp
- Low power consumption: 10 W cooldown and 4.5 W typical with room temperature ambient
- Easy to talk to: Multiple output interfaces including USB-C, MIPI, and Camera Link
- Export friendly: has US Commerce classification as EAR 6A003.b.4.a

Applications

- Thermal imaging
- Soldier Borne and handheld systems
- Security & surveillance
- Small gimbals and SUAS
- Laser See-Spot
- Precision agriculture
- Gas leak detection
- Microscopy
- Medical- tissue analysis
- Structural non-destructive fatigue assessment

The Griffin[™] VGA5-R and Griffin[™] HD5-R camera cores are designed and manufactured in Attollo's 34,000 ft² facility in Camarillo, California. Attollo Engineering specializes in sensors that combine infrared and laser imaging as well as standard and custom IDCA designs for your applications. Attollo is a merchant supplier of standard and custom format III-V detector arrays, hybridized focal plane arrays, and camera assemblies. Attollo Engineering is AS9100 certified.

SYSTEM FEATURES

Griffin™ 5-R Series:	Griffin™ VGA5-R	Griffin™ HD5-R	
Top Level			
Sensor Type	HOT MWIR T2SL		
Sensor Size	640 x 512, 5 μm	1280 x 1024, 5 μm	
Spectral Band	3.0—5.2 µm (Standard) 0.9—5.2 (Broadband) shorter wavelengths available		
NEDT	< 35 mK (50% well fill at T _{bb} = 20°C)		
Frame Rate Options	Typical: 30Hz	Typical: 30Hz	
	Max: 220Hz	Max: 60Hz (HD720p)	
Time to Image	< 2.	< 2.5 min	
Mechanical			
Size (L x W x H)	8.6 cm x 4.2 cm x 4.6 cm		
f/#	f/1.2, f/1.4, f/1.8		
Cold Aperture Height	9.5 mm from FPA		
Weight	< 221 grams		
FPA Characteristics			
Shutter Mode	Snapshot		
Well Capacity	2.2 x 10 ⁶ electrons (effective)		
Quantum Efficiency	> 70%		
Readout Mode	Integrate then read		
Integration Time	0.1 µsec		
Windowing Capable	Yes, max frame rate increases as a function of		
External Sync	row reduction		
Operability		Sync In and Sync Out > 99.5%	
Video Interface			
Parallel (16 bit)	Included		
USB-C	With personality board		
MIPI	With personality board		
Camera Link	With personality board		
Image Processing	AEC, AGC, averaging, histogram equalization		





JS export ense prior to A003.b.4.a. Specifications are subject to change without notice. © 2024 Attollo Engineering LLC. Please scan QR code All rights reserved. XM0000030 REV.2024.4.18

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Interfacing

Shutter Mode	Snapshot	
Well Capacity	2.2 x 10 ⁶ electrons (effective)	
Quantum Efficiency	> 70%	
Readout Mode	Integrate then read	
Integration Time	0.1 µsec	
Windowing Capable	Yes, max frame rate increases as a function of row reduction	
External Sync	Sync In and Sync Out	
Operability	> 99.5%	

LECALUM LECALUM	Equipment described herein is subject to US regulation under EAR and may require a lice export under ECCN 6A003.b.4.a. Specification

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Parallel	50 pin Hirose DF40-50	
Input Voltage	Camera: 5V±10%; Cooler: 12V±10%	
Power Dissipation	10 W cooldown, 4.5 W steady state (23°C), typical	
Communication	USB (USB-C or Camera Link) UART, SPI or I2C (Parallel)	
SDK and GUI Available	Yes	
Cooler Reliability		
Cooler MTTF	>10,000 hours	
Environmental		
	-40°C to +71°C*	
Operating Temperature *In accordance with thermal conside described in the mechanical ICI		
Storage Temperature	-50°C to +85°C	
Max Altitude	40,000 feet	
Humidity	5-95% relative humidity (non-condensing)	
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